

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang

Assignee: Bridge Semiconductor Corporation

Title: METHOD OF MAKING A SEMICONDUCTOR PACKAGE
DEVICE THAT INCLUDES A CONDUCTIVE TRACE WITH
RECESSED AND NON-RECESSED PORTIONS

Serial No.: 10/059,686 Filed: January 29, 2002

Examiner: Zarneke, D. Group Art Unit: 2827

Atty. Docket No.: BDG005-1

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

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SUPPLEMENTAL RESPONSE

OFFICE OF PETITIONS

Please amend the application as follows.

The Claim Amendments begin at page 2.

The Remarks begin at page 18.